

forming a bond between a first surface of a mounting surface of a lens housing and a joint surface of a sidewall of said substrate, said first surface of said mounting surface being parallel to said joint surface; and

forming a bond between a second surface of said mounting surface and an interior surface of said sidewall, said second surface of said mounting surface being perpendicular to said joint surface.

28. A method of forming an optical module comprising:
coupling an image sensor to a base of a substrate;
forming a bond between a first surface of a joint surface of a sidewall of said substrate and a mounting surface of a lens housing; and

forming a bond between a second surface of said joint surface and an exterior side surface of said lens housing.

29. A method of forming an optical module comprising:
coupling an image sensor to a base of a substrate;
forming a bond between a first surface of a joint surface of a sidewall of said substrate and a mounting surface of a lens housing, said first surface of said joint surface being parallel to said mounting surface; and

forming a bond between a second surface of said joint surface and an exterior side surface of said lens housing, said second surface of said joint surface being perpendicular to said mounting surface.

30. A method of forming an optical module comprising:
coupling an image sensor to a base of a first substrate of an image sensor substrate;

coupling a lens housing to said first substrate comprising:

forming a bond between a first surface of a mounting surface of said lens housing and a joint surface of a first sidewall of said first substrate; and